

Low Noise InP HFET Receivers

NRAO Experience



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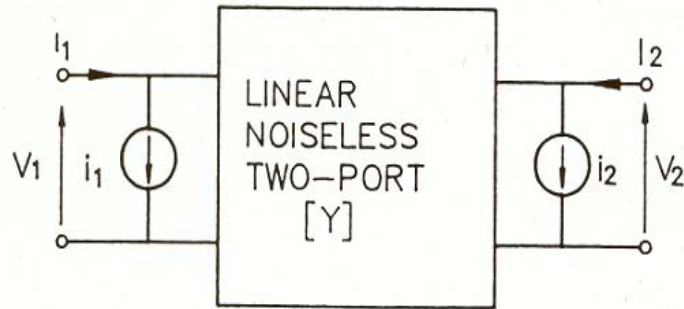
Atacama Large Millimeter/submillimeter Array
Expanded Very Large Array
Robert C. Byrd Green Bank Telescope
Very Long Baseline Array



Outline

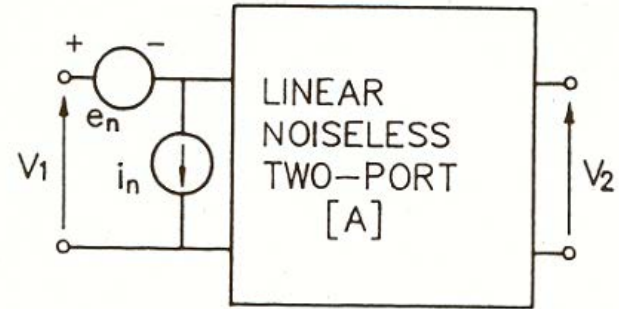
- Limits on noise parameters of microwave transistors
- Accuracy of model predictions
- Limits on noise performance of InP HFETs
- Practical limits on broadband noise matching: examples
- Other factors limiting noise performance of NRAO receivers
- Examples of performance of VLA receivers
- Expected trade-off in very broad band receiver performance

Noise Representations of 2-Ports



$$G_1 = \frac{\overline{|i_1|^2}}{4k T_o \Delta F}, \quad G_2 = \frac{\overline{|i_2|^2}}{4k T_o \Delta F},$$

$$\rho_c = \frac{\overline{i_1^* i_2}}{\sqrt{\overline{|i_1|^2} \overline{|i_2|^2}}}$$



$$g_n = \frac{\overline{|i_n|^2}}{4k T_o \Delta F}, \quad R_n = \frac{\overline{|e_n|^2}}{4k T_o \Delta F},$$

$$\rho = \frac{\overline{e_n^* i_n}}{\sqrt{\overline{|e_n|^2} \overline{|i_n|^2}}}$$

Allowed Values of Noise Parameters (1)

$$T_n = T_{\min} + 4NT_o \frac{|\Gamma_g - \Gamma_{\text{opt}}|^2}{\left(1 - |\Gamma_{\text{opt}}|^2\right) \left(1 - |\Gamma_g|^2\right)}$$

$$\Gamma_{\text{opt}} = \frac{Z_{\text{opt}} - Z_o}{Z_{\text{opt}} + Z_o}$$

$$N = R_{\text{opt}} g_n$$

For all linear noisy two-ports for :

$$|\rho| \leq 1 \quad \text{And therefore}$$

$$\frac{4NT_o}{T_{\min}} \geq 1$$

which is equivalent to correlation matrix being Hermitian and non-negative definite.

Allowed Values of Noise Parameters (2)

$$T_{\min} = T_0 \{ 2N + \operatorname{Re}(\rho \sqrt{R_n g_n}) \} .$$

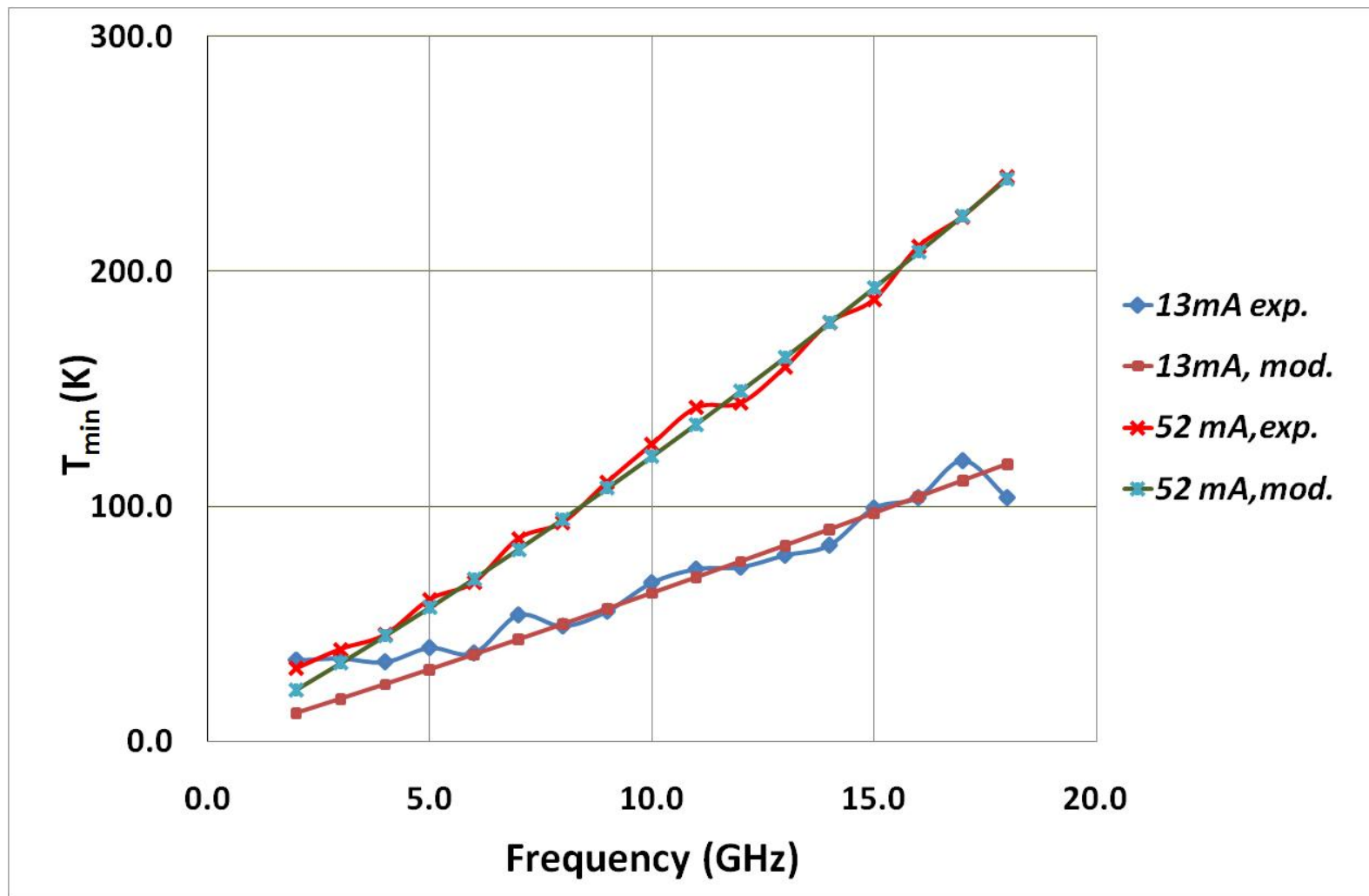
If therefore $\operatorname{Re}(\rho) \geq 0$ and correlation matrix is Hermitian and non-negative definite, than always

$$1 \leq \frac{4NT_0}{T_{\min}} \leq 2$$

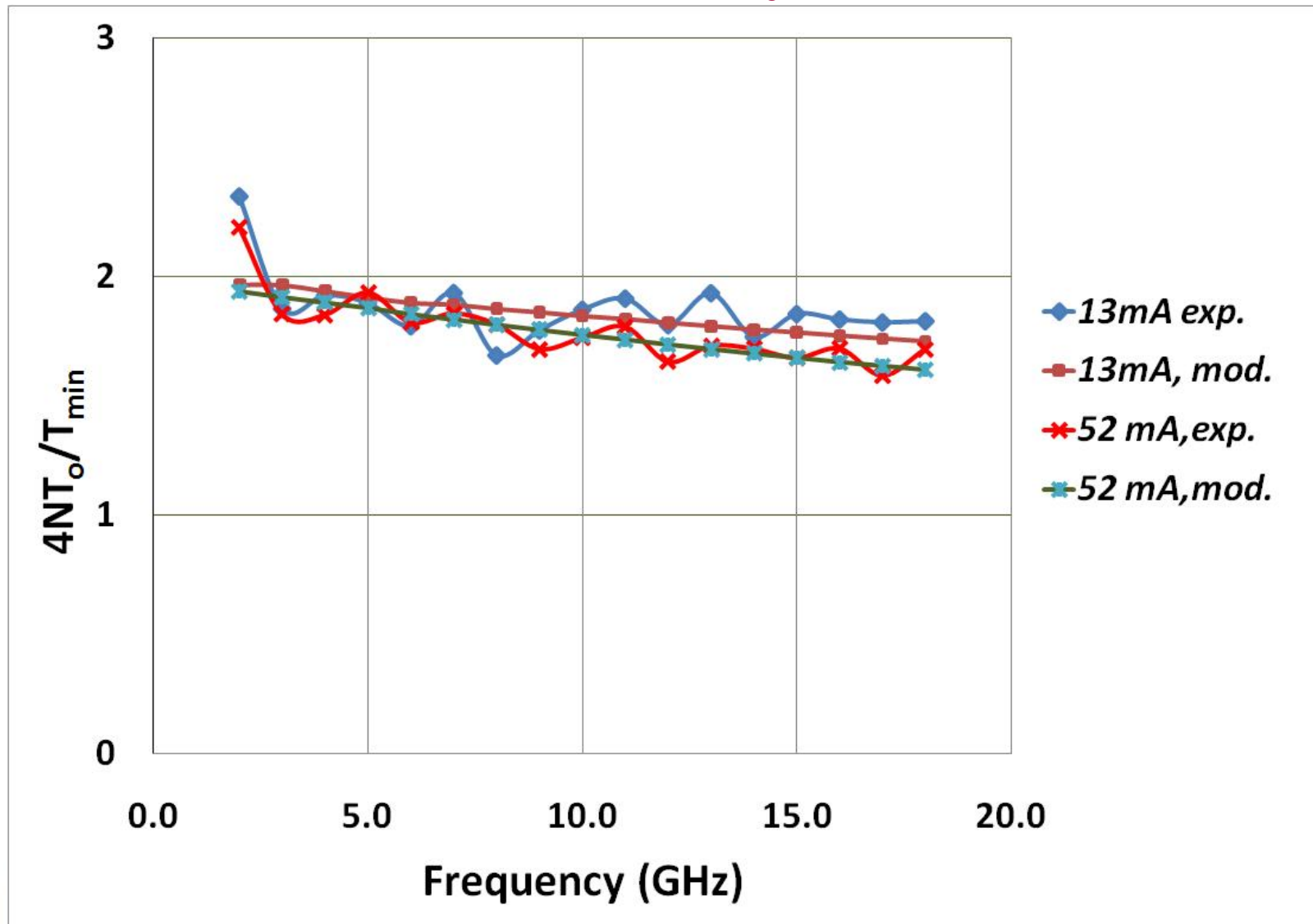
For all microwave transistors
for useful frequency range :

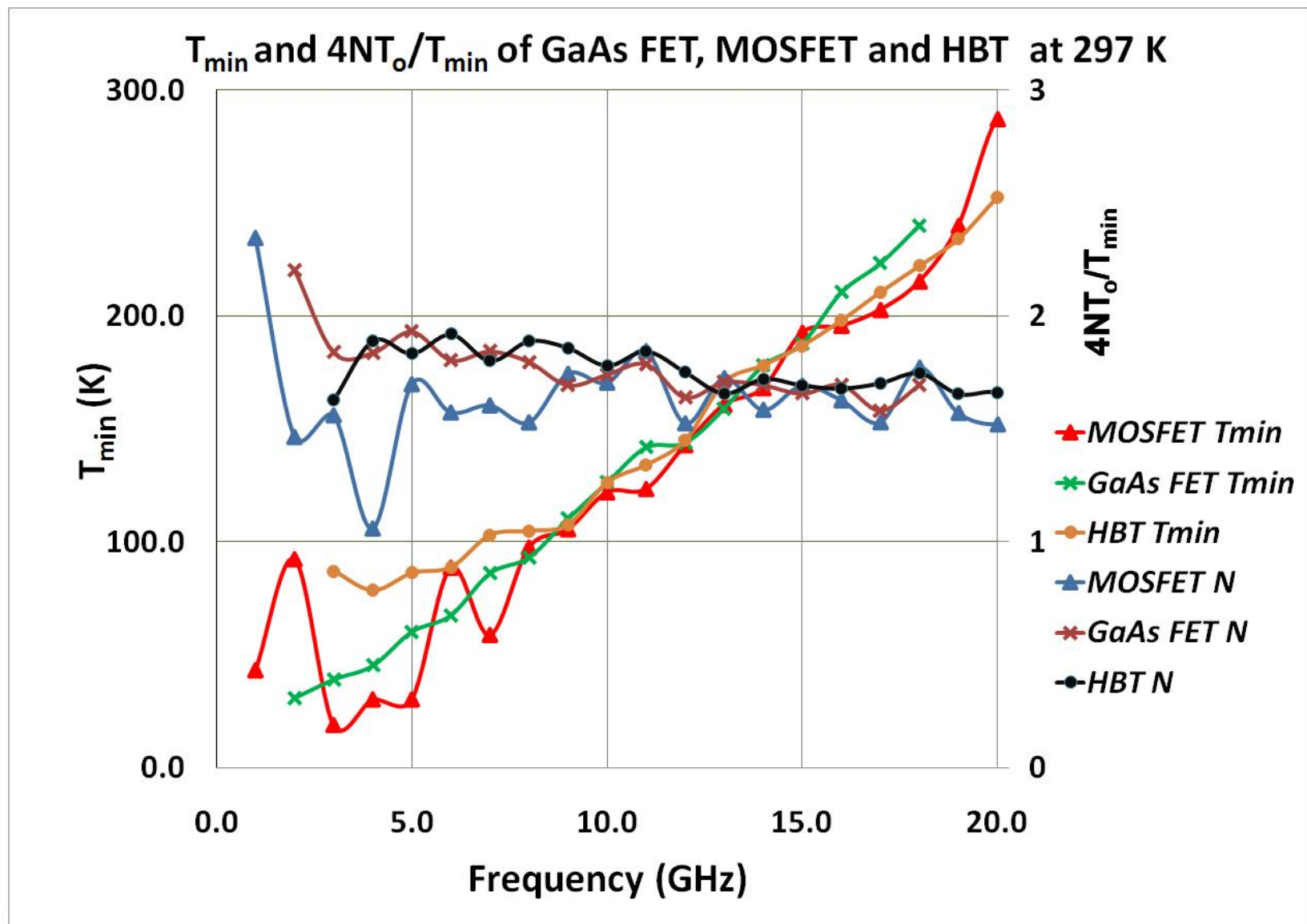
$$\frac{4NT_0}{T_{\min}} \approx 2$$

Measured and Modeled T_{\min} of a FET

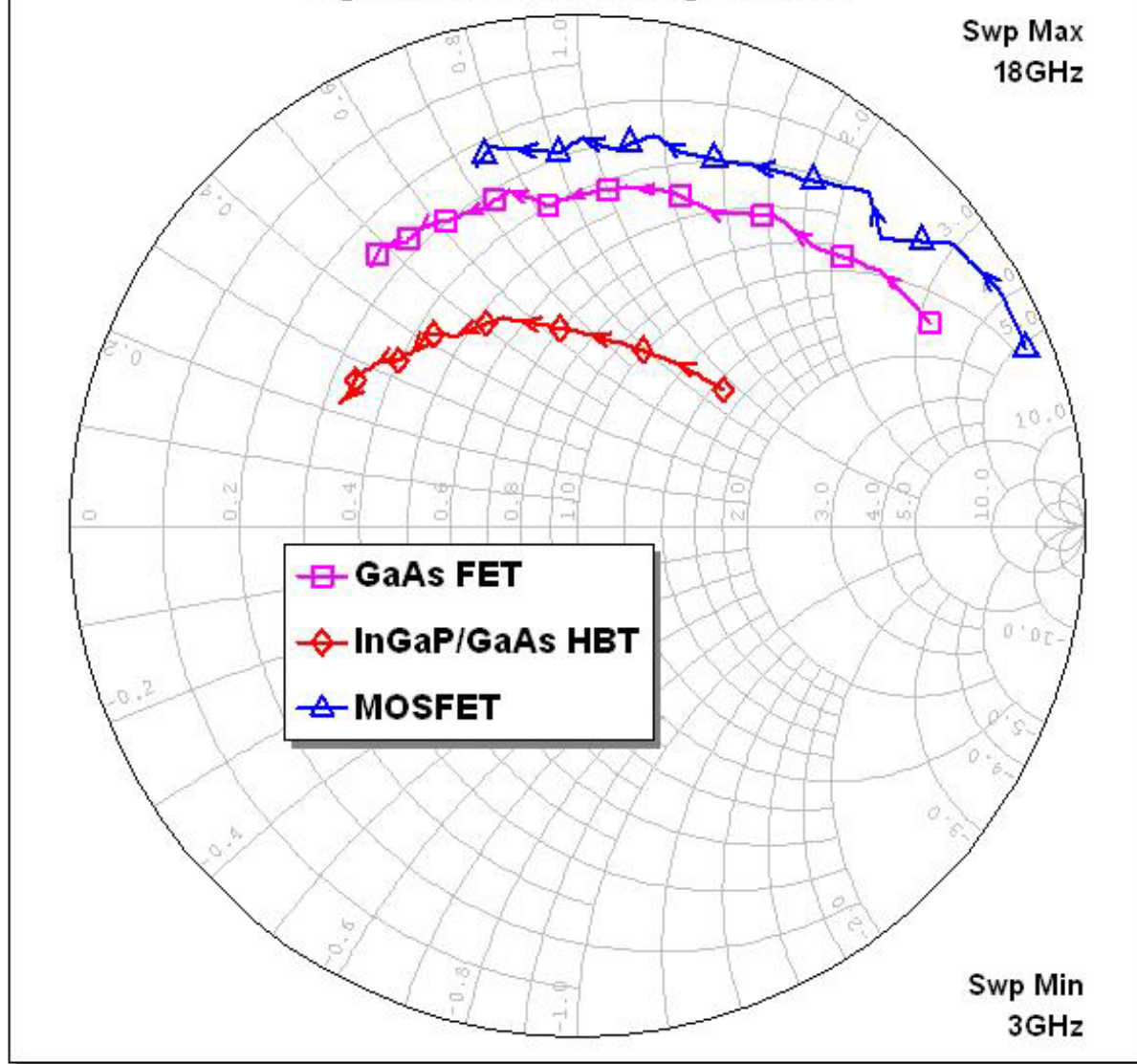


Measured and Modeled $4NT_o/T_{\min}$ of a FET



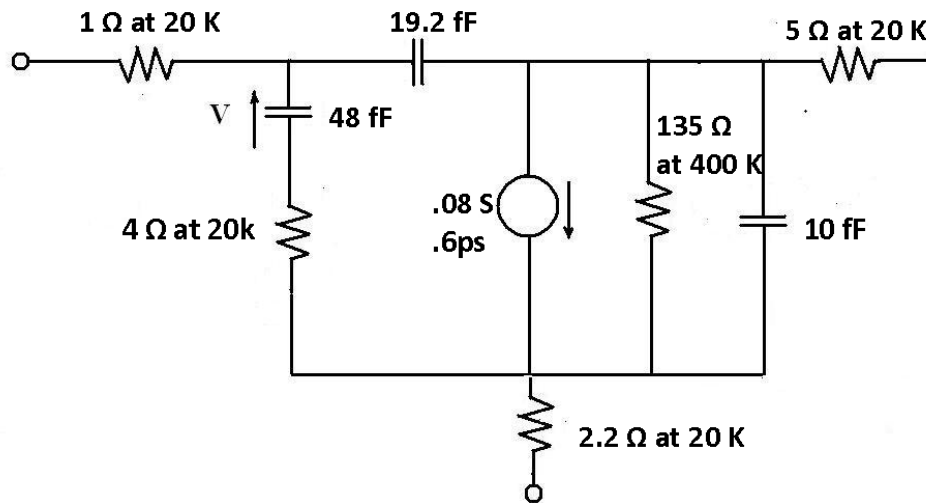


Optimal Source Impedance



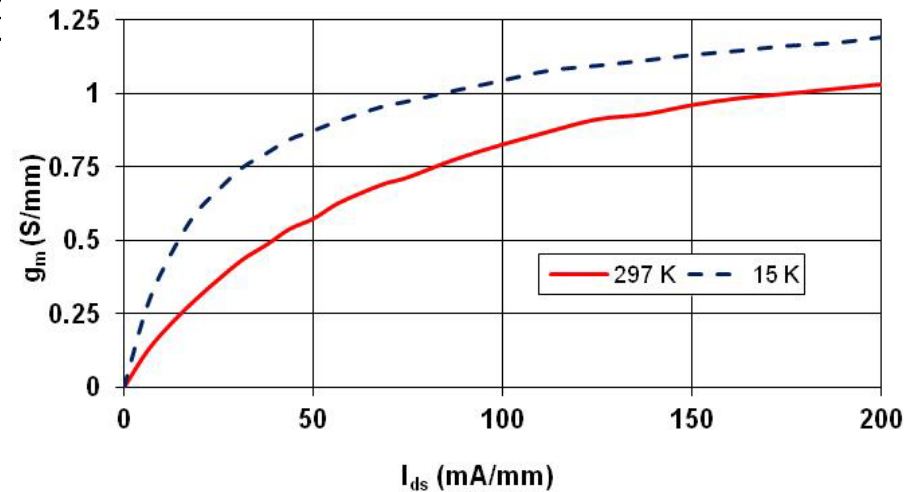
Example of Equivalent Circuit and $g_m(I_{ds})$ Characteristics of Cryo3 InP HFET

Equivalent circuit of cryo3 device



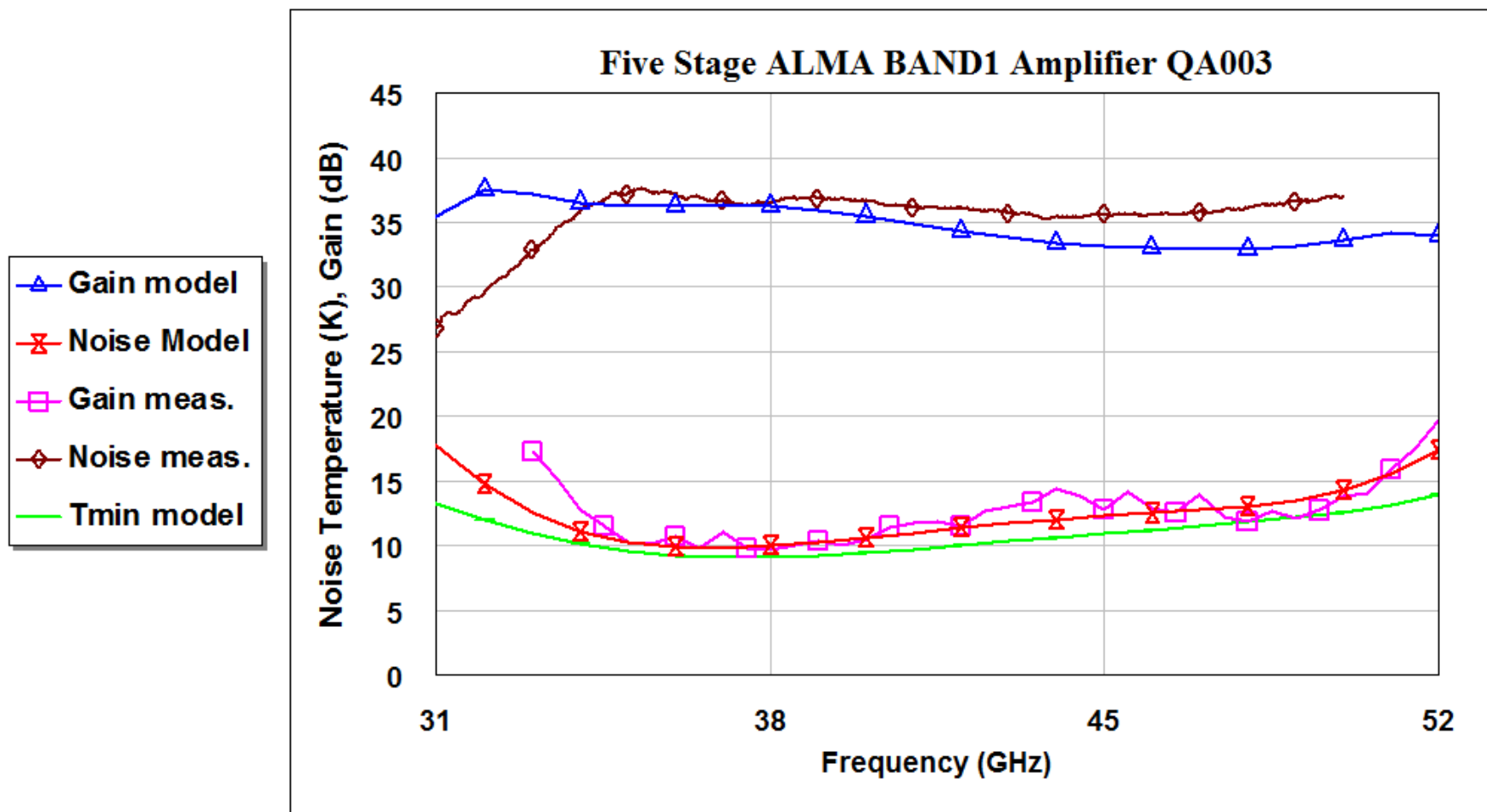
$L_g=80\text{nm}$, $W_g=80\mu\text{m}$

$g_m(I_{ds})$ characteristics

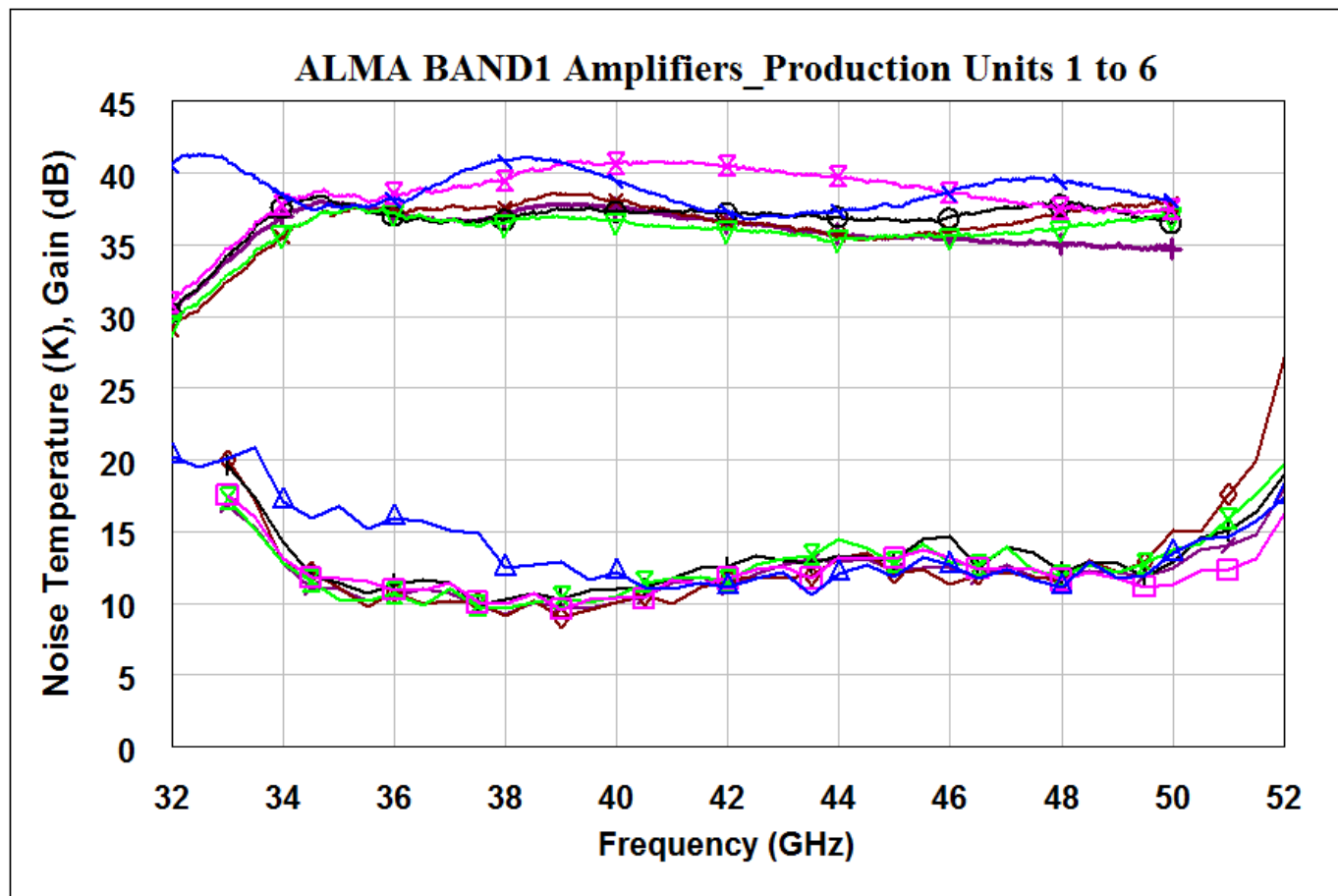
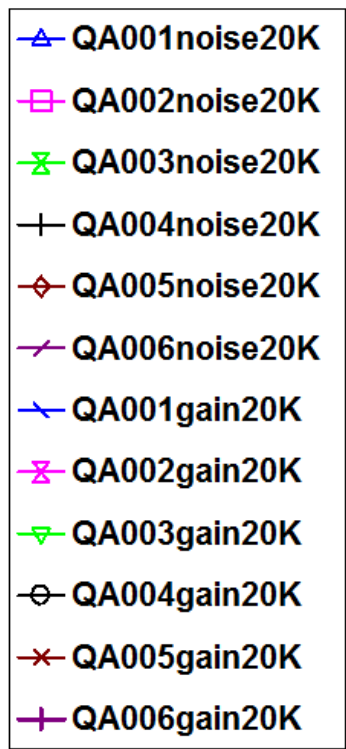


$$T_{\min} \cong 2 \frac{f}{f_t} \sqrt{g_{ds} T_d r_t T_g} \cong \frac{f}{f_{\max}} \sqrt{T_d T_g}$$

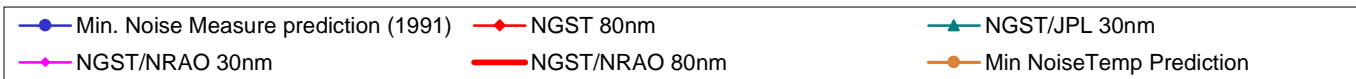
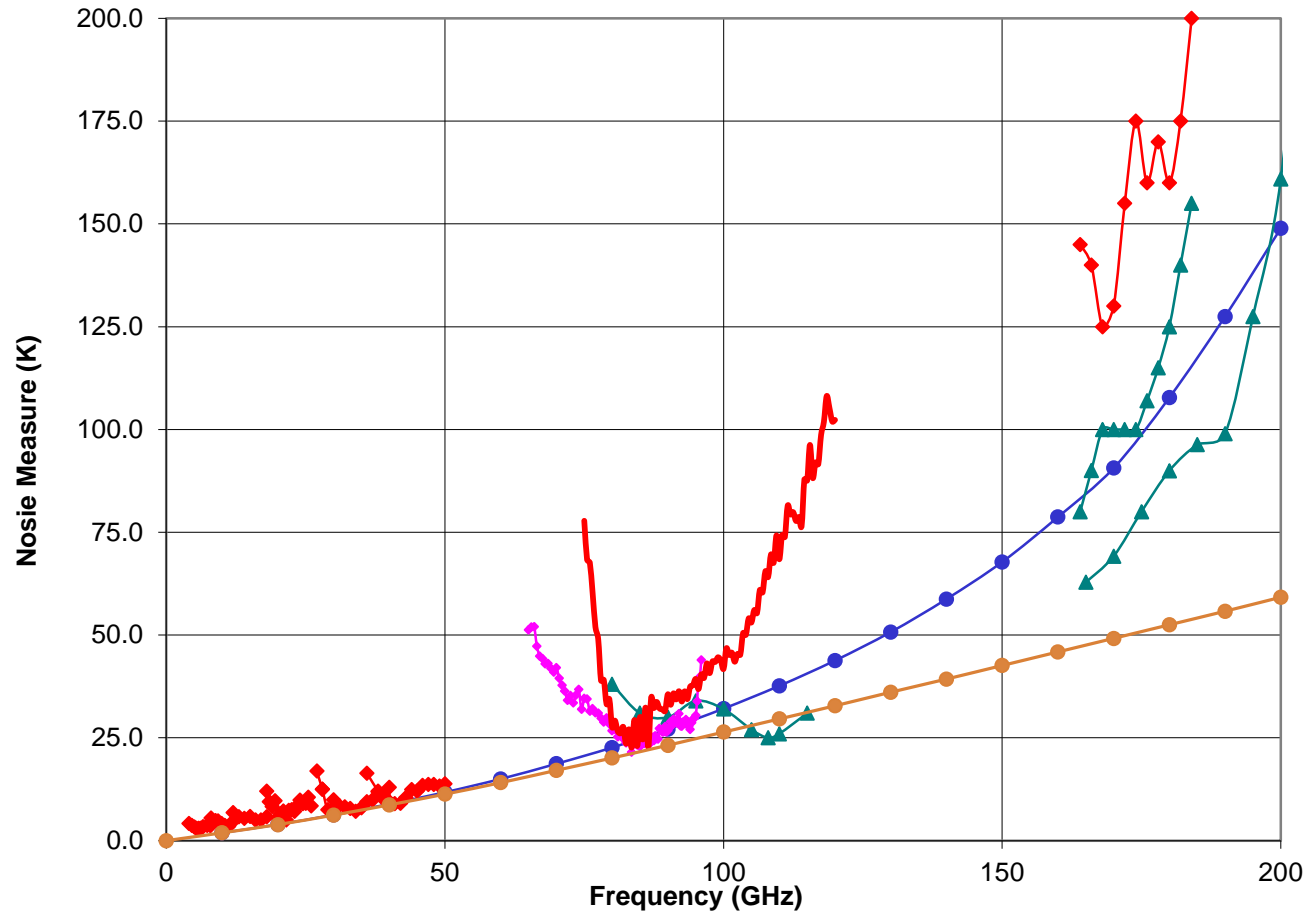
5 stage 33-52 GHz amplifier: model and measured results at 20 K



33-52 GHz amplifiers: First Six Units at 20 K



Noise Temperature Summary of Cryogenic HEMTs



Device Scaling: Gate Length (1)

$$T_{\min} \cong 2 \frac{f}{f_t} \sqrt{g_{ds} T_d r_t T_g} \cong \frac{f}{f_{\max}} \sqrt{T_d T_g} \quad f_t \cong \frac{g_m}{2\pi(C_{gs} + C_{gd})}$$

L_g  f_{\max}  T_{\min}  if $T_d \approx \text{const.}$

$T_g \cong \text{Ambient temp.}$ T_d depends on gate length, channel structure, and current density I_d/mm but mostly not on ambient temperature

For every device structure there must exist a lower limit on T_{\min} upon further device scaling. Exact dependence of T_d on device structure and properties of electron transport in the channel is not known, but

Device Scaling: Gate Length (2)

within a measurement error no device demonstrated T_{\min} lower than that predicted in MMA Memo #67 (1991)

The best cryogenic wafers: Chalmers (130 nm), NGSTCryo3 (80-100 nm), NGST (35 nm) exhibit progressively better f_{\max} and M_{\min}

but about the same minimum T_{\min} because T_d increases for deep submicron gate lengths.

The reasons:

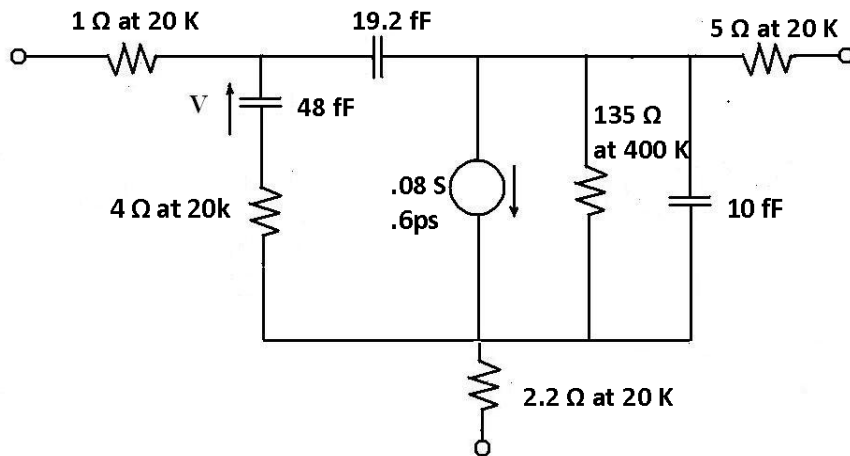
- Noise optimal bias minimizing the value of : $f(V_{ds}, I_{ds}) \approx \frac{\sqrt{I_{ds}}}{g_m}$ increases for (shorts channel effects).
- Also T_d increases for the same value of I_d/mm (no explanation yet).

For $f_{\max}=\text{const.}$ and constant bias:

$$T_{\min} \propto \sqrt{T_a}$$

Plausible Explanation ?

Equivalent circuit of cryo3 device



Shot noise in the drain?

Assume:

$$4kT_d = 2qI_d$$

Then for $I_d = 3\text{mA}$

$$T_d \approx 4700\text{ K}$$

$L_g = 80\text{nm}$, $W_g = 80\mu\text{m}$, $V_{ds} = .8\text{V}$, $I_{ds} = 3\text{ mA}$

$$T_{\min} \cong 2 \frac{f}{f_t} \sqrt{g_{ds} T_d r_t T_g} \cong \frac{f}{f_{\max}} \sqrt{T_d T_g}$$

Device Scaling: Gate Width

$$T_{\min} \cong 2 \frac{f}{f_t} \sqrt{g_{ds} T_d r_t T_g}$$

$$R_{\text{opt}} \cong \frac{f_t}{f} \sqrt{\frac{r_t T_g}{g_{ds} T_d}}$$

$$r_t = r_{gs} + r_g + r_s$$

Width 

R_{opt} 

T_{\min} 

in principle

T_{\min} 

in practice

Important Notes:

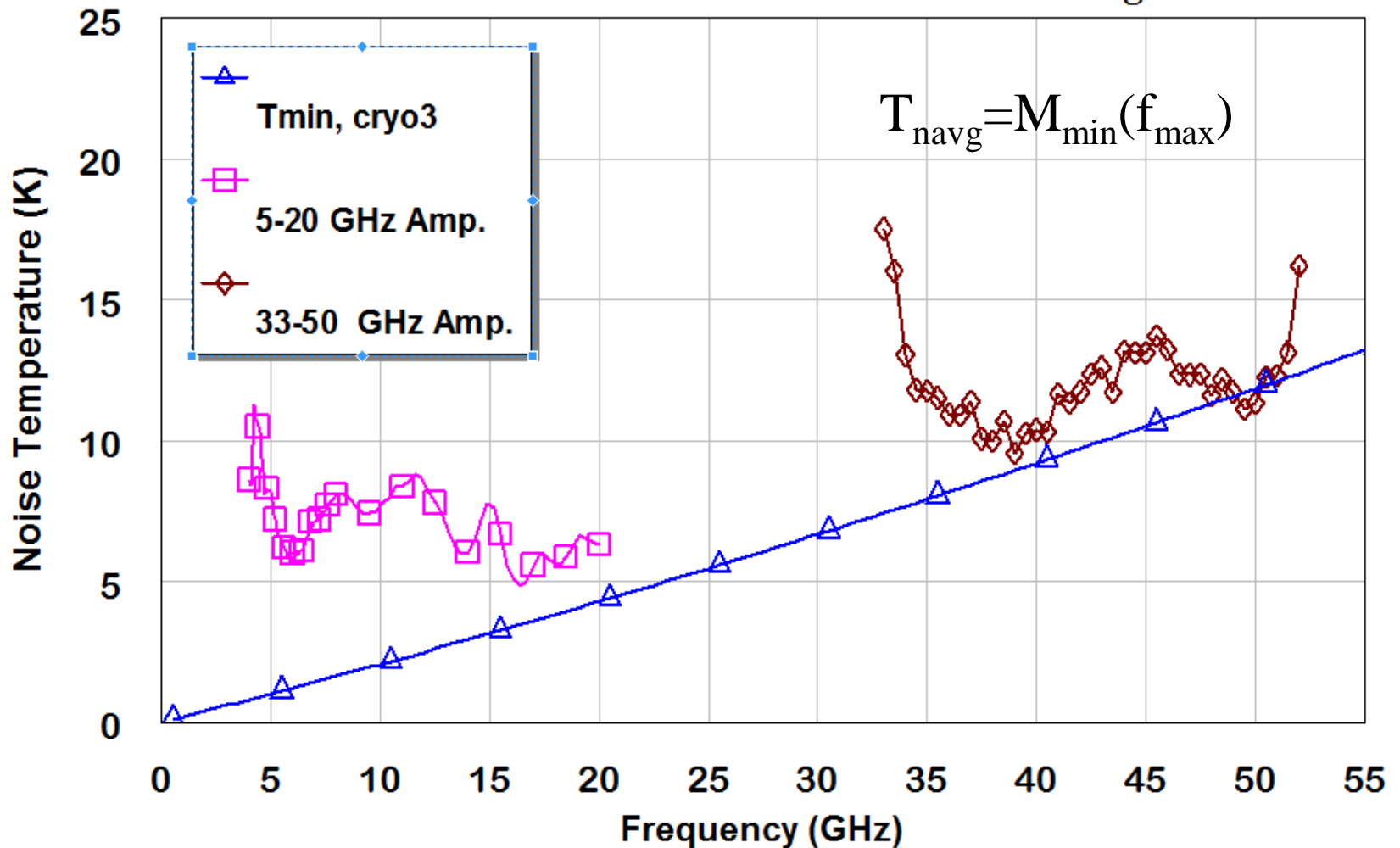
$$T_n = T_{\min} + 4NT_0 \frac{|\Gamma_g - \Gamma_{\text{opt}}|^2}{\left(1 - |\Gamma_{\text{opt}}|^2\right)\left(1 - |\Gamma_g|^2\right)} \xrightarrow[\Gamma_g=0]{\frac{4NT_0}{T_{\min}} \cong 2} T_n \cong T_{\min} \frac{|\Gamma_{\text{opt}}|^2}{\left(1 - |\Gamma_{\text{opt}}|^2\right)}$$

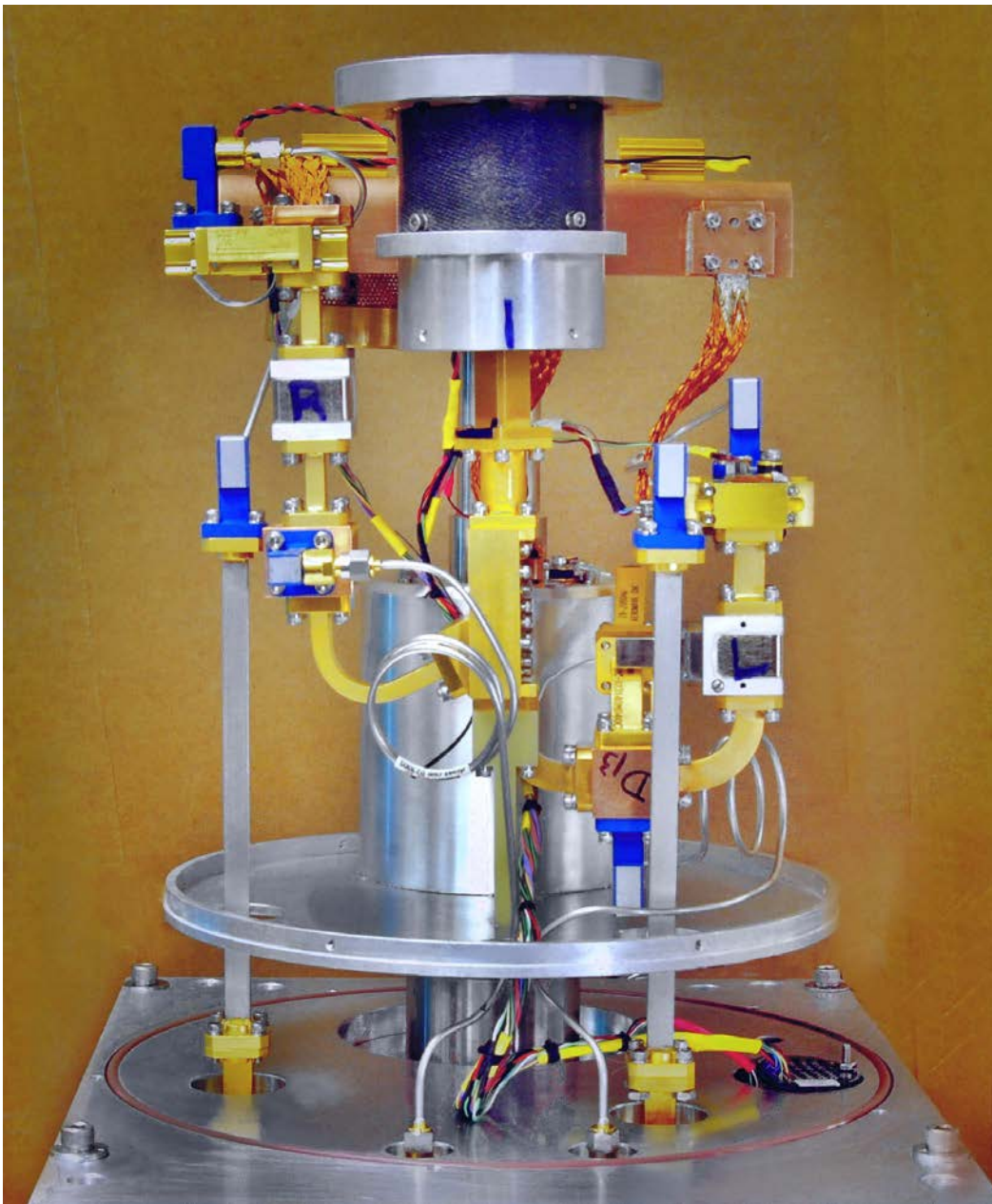
For a given frequency range chose Γ_{opt} close to SC center.

In practice, for a given frequency range average T_n is:

$$\frac{1}{f_{\max} - f_{\min}} \int_{f_{\min}}^{f_{\max}} T_n df \approx M_{\min}(f_{\max})$$

Illustration of Wide Band Noise Matching



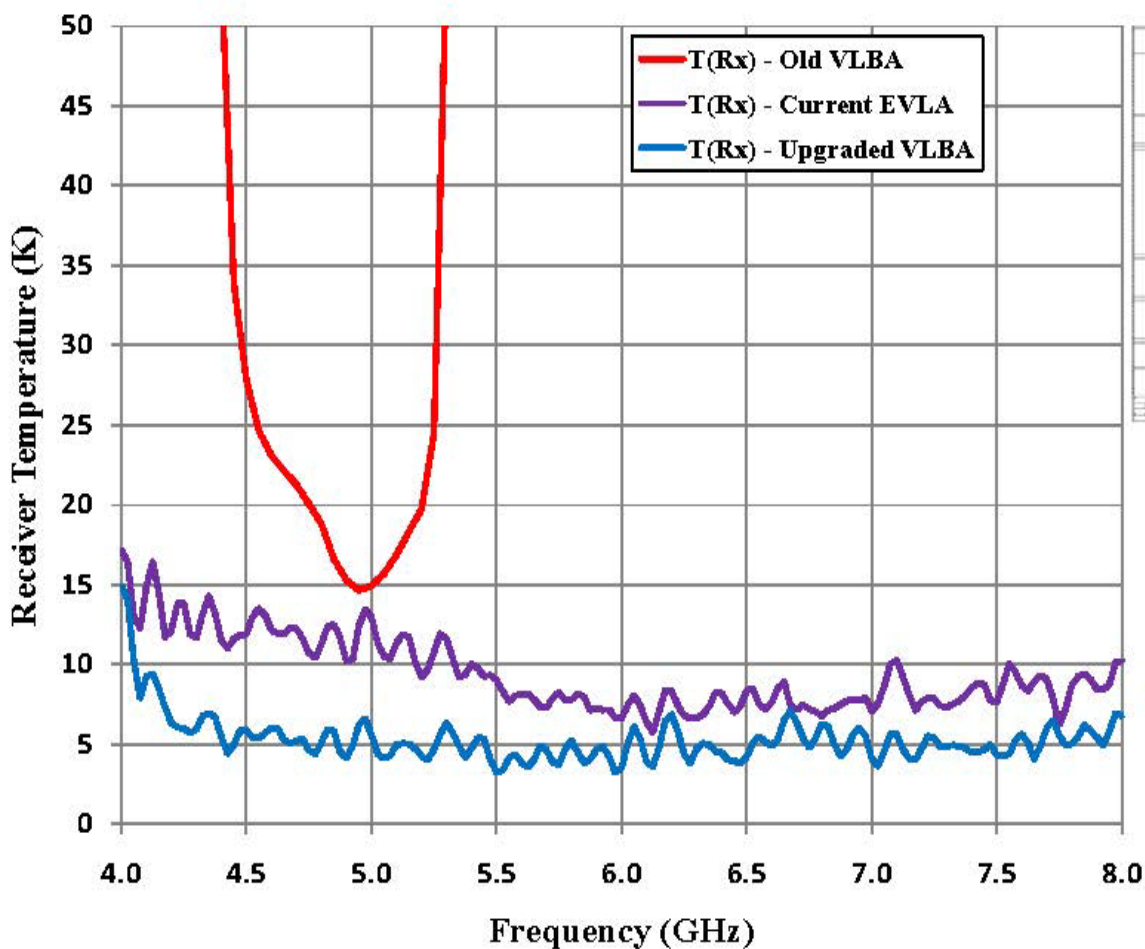


JVLA K_a - Band Receiver

Courtesy: R. Hayward,
P. Harden, NRAO

Prototype VLBA C-Band (S/N 11) Sensitivity

Old VLBA vs. New VLBA vs. EVLA Receivers



5/5th
4/5th
3/5th
2/5th

The ripple seen in the baseline of the EVLA & new VLBA receivers come from using only the 3 lower sections of the 5 piece EVLA feed so that a smaller 12" diameter Cold Load can be utilized for the Y-Factor measurements. The full feed will add 1-2°K to the T(Rx)..

Installing the Goretex RA3T20 radome over the mouth of the feed would add <1°K to the noise temperature.

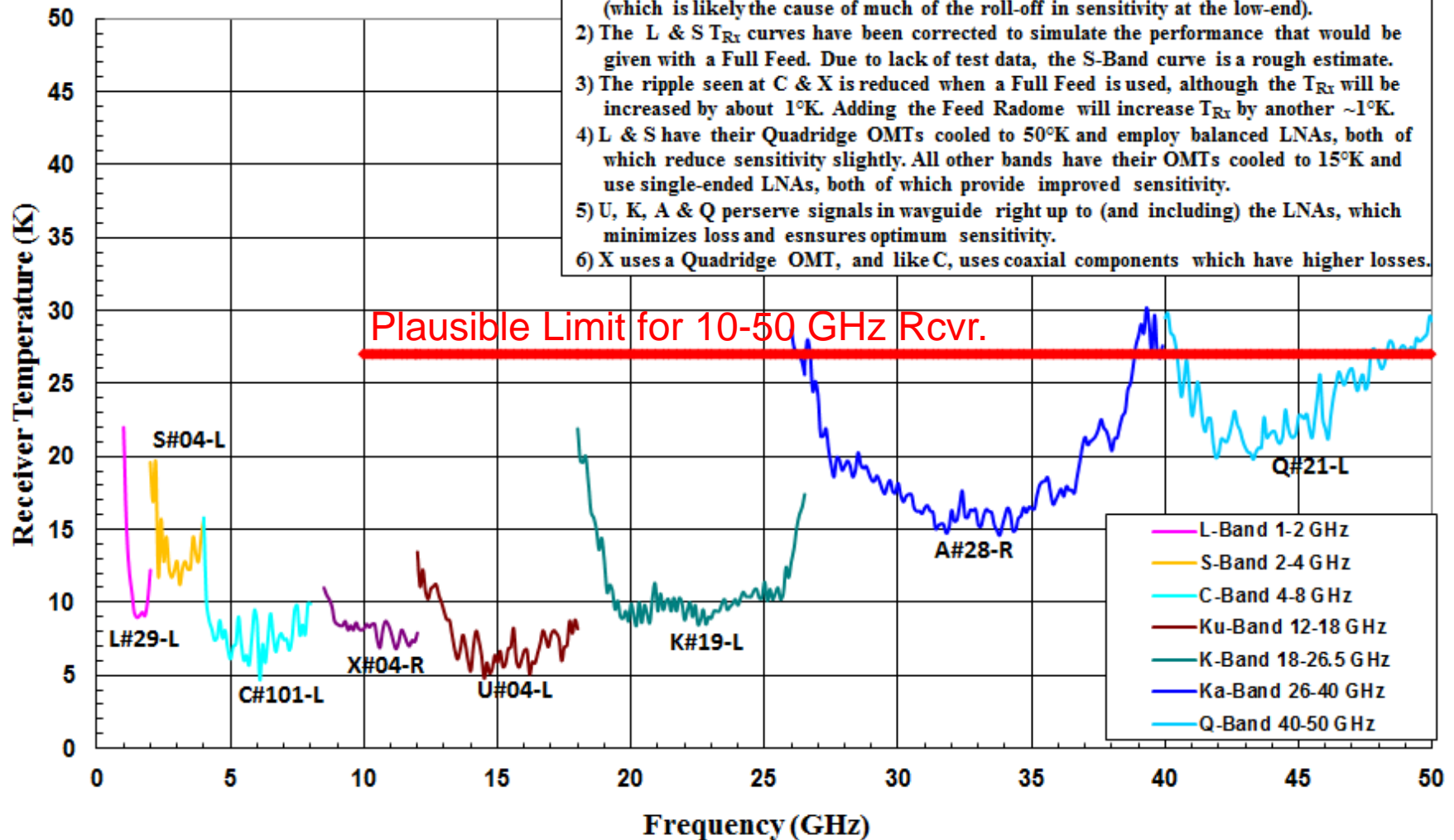
The new upgraded VLBA C-Band receiver has better sensitivity over the receiver now in use on the EVLA thanks to a new improved Thermal-Gap assembly.

Courtesy: R. Hayward

T(Rx) vs. Frequency for JVLA Receiver Bands

(RHH : 5 June 2012)

- 1) L & S evaluated with External OMT test fixtures which provide Coaxial Hot and Cold Loads. All other bands are tested with Partial (C & X) or Full (U, K, A & Q) sized Feeds (which is likely the cause of much of the roll-off in sensitivity at the low-end).
- 2) The L & S T_{Rx} curves have been corrected to simulate the performance that would be given with a Full Feed. Due to lack of test data, the S-Band curve is a rough estimate.
- 3) The ripple seen at C & X is reduced when a Full Feed is used, although the T_{Rx} will be increased by about 1°K. Adding the Feed Radome will increase T_{Rx} by another ~1°K.
- 4) L & S have their Quadridge OMTs cooled to 50°K and employ balanced LNAs, both of which reduce sensitivity slightly. All other bands have their OMTs cooled to 15°K and use single-ended LNAs, both of which provide improved sensitivity.
- 5) U, K, A & Q preserve signals in waveguide right up to (and including) the LNAs, which minimizes loss and ensures optimum sensitivity.
- 6) X uses a Quadridge OMT, and like C, uses coaxial components which have higher losses.



Courtesy: R. Hayward

Summary

- Only three wafer runs of InP discrete devices (NRAO/HRL, WMAP/HRL, NGST/JPL cryo3) have been used in construction of great majority of radio astronomy instruments: VLA/EVLA, VLBA, GBT, ALMA band6, CBI, SZ-Array, WMAP, Planck LFI (K_a and Q), VSA, AMI, MPI, JPL/DSN and others
- No single wafer devices have ever been fully understood
- There has been no significant progress in the low noise performance of cryogenic HFET's in the past 15 years; Are we approaching the limits?
- Amplifier noise temperature is no longer the dominant component of the system noise for radio astronomy instruments with cryogenic receivers
- Very broadband receivers will suffer loss of sensitivity which can be well predicted, with accuracy satisfactory for the assessment of possible benefits